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Vedi allegato

# SECO showcases its comprehensive Edge AI platform strategy at embedded world 2026

*Arezzo, March 10, 2026* – SECO S.p.A. ("**SECO**" or the "**Company**"), a leading provider of edge computing and AI-driven digitalization solutions, will present its most comprehensive technology portfolio to date at Embedded World 2026 starting today in Nuremberg, Germany.

The Company will introduce new hardware platforms, software capabilities, and live demonstrations that underline SECO's role as a strategic partner enabling the industrial transition to intelligent, connected, service-oriented products. The expanded lineup reflects SECO's continued growth across industrial, medical, vending, mobility, and smart infrastructure markets.

Key highlights include:

- **Qualcomm Collaboration** – Launch of new Dragonwing based solutions, including the SOM-COMe-CT6-Dragonwing-IQ-X and upcoming SMARC/COM HPC platforms. These systems deliver high performance, real time, cloud independent AI for automation, computer vision, and robotics in demanding industrial environments;

- **Intel Partnership** – Introduction of platforms featuring Intel Core Ultra Series 3 and Intel Atom processors, led by the SOM-COMe-BT6-PTL. A live demo developed with Reply demonstrates software defined automation and edge native intelligence, showcasing SECO's ability to modernize legacy industrial assets;

- **NXP Ecosystem Expansion** – Debut of Modular Vision 10.1 MX95 and SOM-SMARC-MX95, secure and scalable HMI and embedded platforms built on the new i.MX 95 processors. The solutions integrate functional safety, advanced security features, and long term lifecycle support for mission critical applications;

- **MediaTek Edge AI Portfolio** – Presentation of the new SOM-Trizeps-X-Genio360 and the Modular Vision Genio700 HMI. These platforms address cost efficient Edge AI, advanced HMIs, and on device inference across medical, industrial, and mobile systems, expanding SECO's addressable market;

- **Clea Software Framework** – Demonstrations of Clea as SECO's unified AI and IoT software layer, enabling secure fleet management, OTA updates, data orchestration, and scalable deployment of containerized AI. Live showcases – including MUSAI and multiple HMI experiences – illustrate Clea's ability to turn edge devices into service ready digital assets;

- **SECO Cybersecurity Offering** – SECO will showcase its cybersecurity framework for protecting connected devices across their entire lifecycle. The offering includes vulnerability management, secure software updates, device monitoring, and compliance support, enabling OEMs to deploy and operate resilient connected products aligned with emerging regulations such as the Cyber Resilience Act;

- **Smart Vending & Payments** – Presentation of a production ready vending solution integrating Clea Vend and the KarL4 contactless payment terminal. Following strong nationwide penetration in Germany, the platform is now scaling into Italy and the United States, demonstrating SECO's ability to pair embedded hardware with cloud analytics and recurring revenue digital services.

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**PRESS RELEASE**

Together, the showcased innovations highlight SECO's integrated Edge AI strategy, bringing together advanced hardware, its AI and IoT software framework Clea, and application enablement capabilities through the SECO Application Hub into a scalable, end-to-end ecosystem.

*"At this year's Embedded World, SECO is demonstrating the depth and maturity of a full Edge to AI platform strategy,"* said **Massimo Mauri, CEO of SECO**. *"Through close collaboration with our silicon partners and accelerating adoption of Clea, we are helping customers transform their products into intelligent, connected, and service-enabled solutions."*

Visitors can experience SECO's full showcase at **Hall 1, Booth 320**.

**SECO**

SECO (IOT.MI) is a high-tech company that develops and manufactures cutting-edge solutions for the digitalization of industrial products and processes. SECO's hardware and software offerings enable B2B companies to easily introduce edge computing, Internet of Things, data analytics, and artificial intelligence to their businesses. SECO's technology spans across multiple fields of application, serving more than 450 customers across sectors such as medical, industrial automation, fitness, vending, transportation, and many others. Through live monitoring and smart control of in-the-field devices, SECO solutions contribute to low environmental impact business operations via a more efficient use of resources.

For more information: http://www.seco.com/

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| Fine Comunicato n.2358-14-2026 | Numero di Pagine: 4 |
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